

1310nm MQW-FP Laser Diode with pigtail for OTDR(8-12mW)**HEFOP-3XXXXXXX****Features:**

- ◆ High stability FP laser chip
- ◆ High Power
- ◆ Operate Temperature from -40°C to +85°C

Applications:

- ◆ Optical Time Domain Reflectometer (OTDR)
- ◆ High power laser for instrument

General:

HEFOP-3XXXXXXX is a 1310nm Multiple Quantum Well (MQW) structured Fabry-Perot (FP) laser diode coaxial module with single mode fiber. This module is specified to operate under pulsed condition and designed for light source of Optical Time Domain Reflectometer (OTDR).

Absolute Maximum Ratings: ^{*Note1}

Parameter	Symbol	Ratings	Unit
Storage Temperature	Tstg	-40~+85	°C
Operating Case Temperature	Top	-40~+85	°C
Soldering Temperature (<10s)	Stemp	260	°C

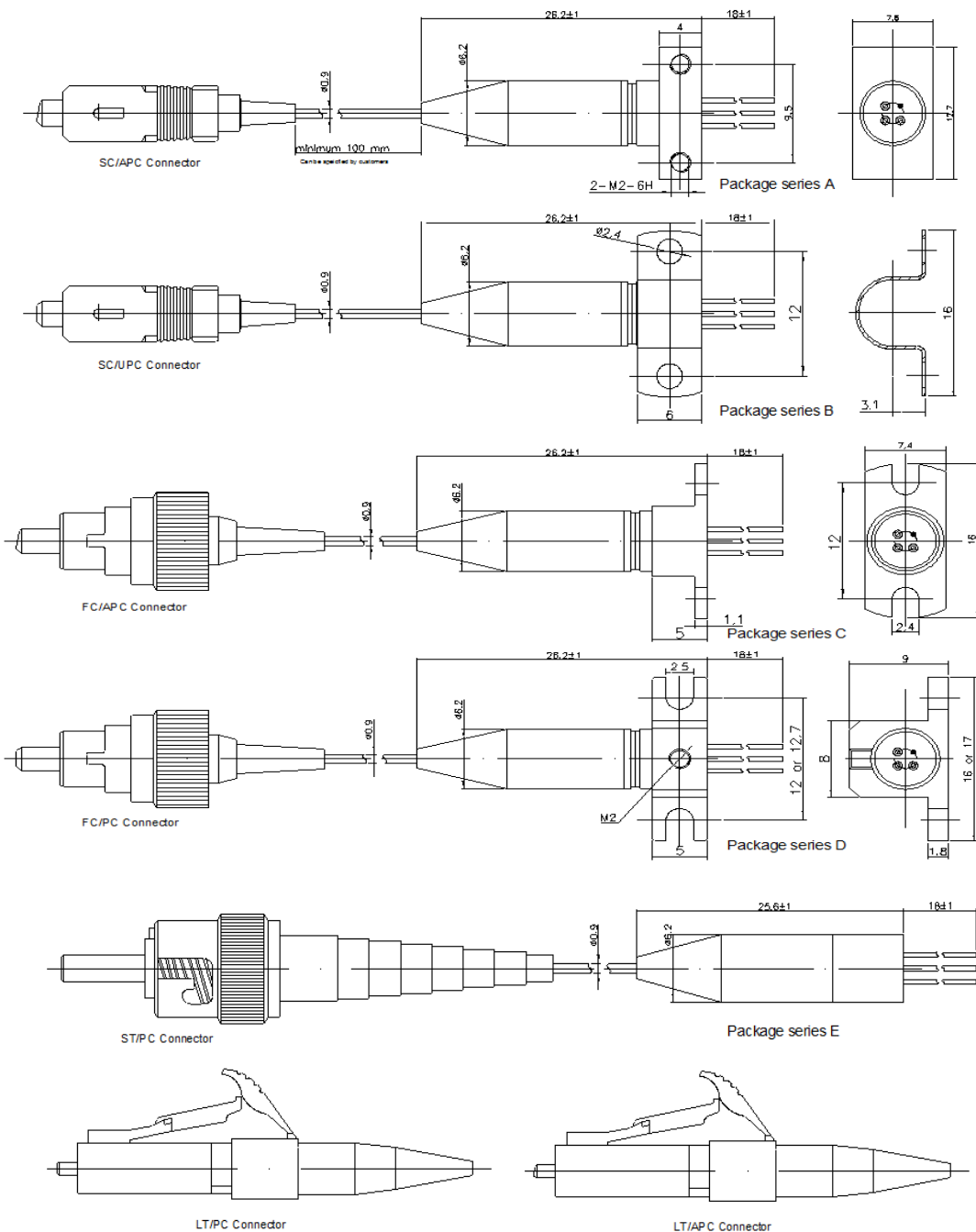
*Note1: Exceeding any one of these values may destroy the device immediately.

Electrical and Optical Characteristics:

(Tc=+25°C, unless otherwise noted.)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Optical Output Power (pulse mode)	Pf	IFP=100mA, PW=10μS, Duty=1%	15	20	—	mW
		IFP=200mA, PW=10μS, Duty=1%	25	45	—	
		IFP=350mA, PW=10μS, Duty=1%	60	75	—	
		IFP=400mA, PW=10μS, Duty=1%	70	110	—	
Threshold Current	Ith	T=25°C, Iop=50mA	—	8	15	mA
Output Power	Po	CW, Iop=50mA	8	12	—	mW
Operating Current	If	CW, T=25°C	—	—	100	mA
Operating Voltage	Vf	CW, Iop=50mA	—	1.2	2.0	V
Center Wavelength	λ _c	CW, T=25°C	1290	1310	1330	nm
Spectral Width(-20dB)	Δλ	CW, T=25°C	—	—	3.5	nm
Rise/Fall Times	t _R , t _F	10% to 90%	—	0.2	2	ns
Monitor Current	I _m	CW, Iop=50mA	100	—	—	uA
Monitor Dark Current	I _d	CW, Vr=5V	—	—	0.1	uA

Pigtail Package Dimension: *Note2、3、4



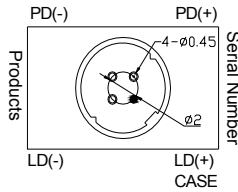
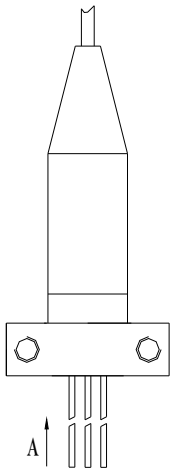
*Note2: PIN direction and laser mark can be customized. Pigtail is standard SM fiber; the length also can be customized.

*Note3: For the package series D, the clamping rings dimensions (A) and drill size (B) are can be selected. The following types can be available. Please designate the detailed type while ordering the package series D.

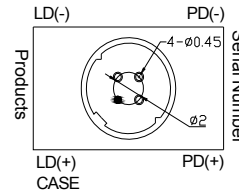
Fixed card type	A(mm)	B(mm)
D	16	12
D-S	17	12.7

*Note4: For the package series B, the fix card is fixed by customer self. For the detailed information of fix card of A, C, D package series, please refers the following graphs.

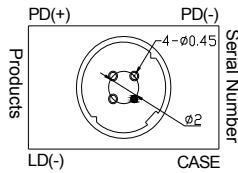
The Direction of Fix Card:



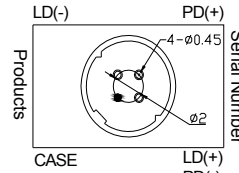
Direction A view
PLD1A-1(DEFAULT)



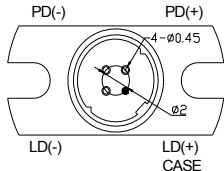
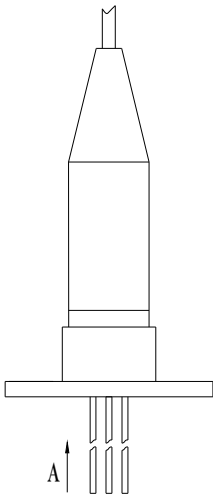
Direction A view
PLD1A-2



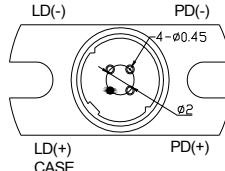
Direction A view
PLD2A-1(DEFAULT)



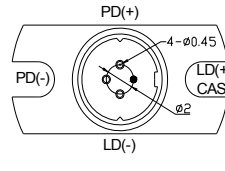
Direction A view
PLD2A-2



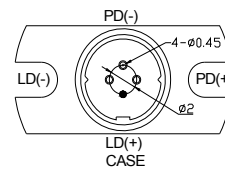
Direction A view
PLD1C-1(DEFAULT)



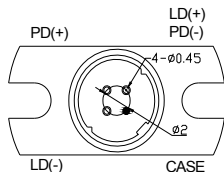
Direction A view
PLD1C-2



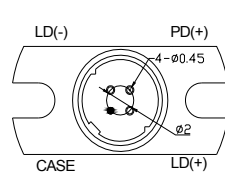
Direction A view
PLD1C-3



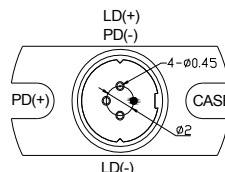
Direction A view
PLD1C-4



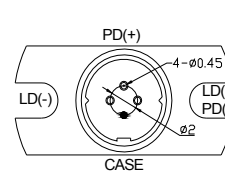
Direction A view
PLD2C-1(DEFAULT)



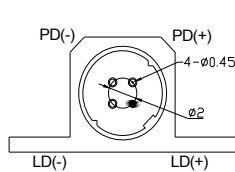
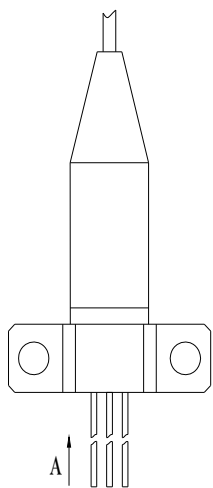
Direction A view
PLD2C-2



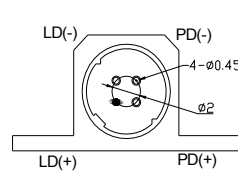
Direction A view
PLD2C-3



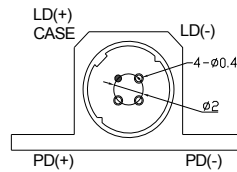
Direction A view
PLD2C-4



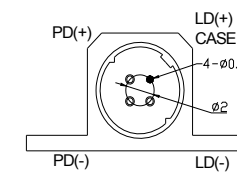
Direction A view
PLD1D-1(DEFAULT)



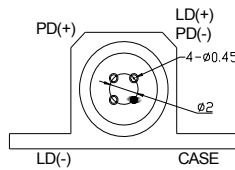
Direction A view
PLD1D-2



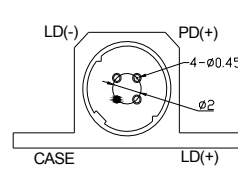
Direction A view
PLD1D-3



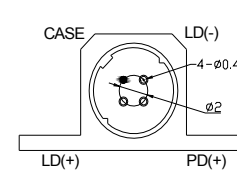
Direction A view
PLD1D-4



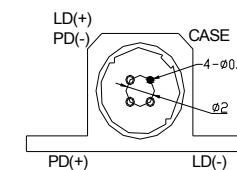
Direction A view
PLD2D-1(DEFAULT)



Direction A view
PLD2D-2

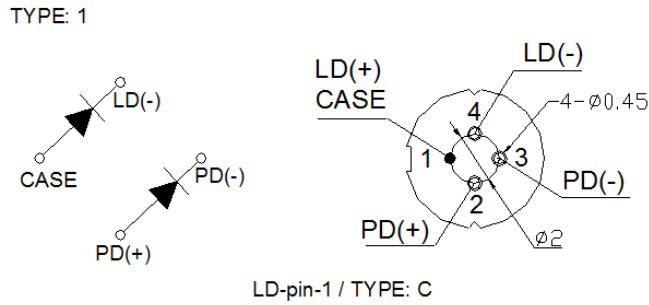


Direction A view
PLD2D-3



Direction A view
PLD2D-4

Pin Assignment:



Nomenclature:

HEFOP —3

A B C D E F G

NO	Parameter	Detailed Description							
A	Wavelength	3=1310							
B	Data Rate	2=2.5G							
C	Power	80=8-12mW							
D	Package Series	A	B	C	D	E			
E	Connector	F=FC/PC		S=SC/PC		T=ST/PC		L=LC/PC	
		FA=FC/APC		SA=SC/APC		Blank=None			
F	Pin Type	1=LD-pin-1							
G	Isolator	Blank=None		G= Single Stage		G2=Dual Stage			

Precaution:

- (1) The modules should be handled in the same manner as ordinary semiconductor devices to prevent the electro-static damages. For safe keeping and carrying, the modules should be packaged with ESD proof material. To assemble the modules on PCB, the workbench, the soldering iron and the human body should be grounded.
- (2) Please pay special attention to the atmosphere condition because the dew on the module may cause some electrical damages.
- (3) Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed.

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